L Numb r	Hits	S arch T xt	DB	Tim stamp
numb r	2211	359/223-226,290-291. cls.	USPAT;	2004/06/21
			US-P PUB;	
			EPO; JPO;	
			DERWENT	
_	32998	MEMS	USPAT;	2004/06/21
	02000		US-PGPUB;	1
			EPO; JPO;	****
			DERWENT	
-	6064	bimorph	USPAT;	2004/06/21
	0004	Виногри	US-PGPUB;	
			EPO; JPO;	07.43
			DERWENT	
	20	250/222 226 200 204 colo and MEMS and		2004/06/24
-	28	359/223-226,290-291.ccls. and MEMS and	USPAT;	2004/06/21
		bimorph	US-PGPUB;	07:44
			EPO; JPO;	
	05000		DERWENT	0004/00/04
-	252225	silicon and aluminum	USPAT;	2004/06/21
			US-PGPUB;	07:44
			EPO; JPO;	
			DERWENT	
-	35	bimorph same (silicon and aluminum)	USPAT;	2004/06/21
			US-PGPUB;	07:45
			EPO; JPO;	
			DERWENT	
•	240891	silicon with substrate	USPAT;	2004/06/21
			US-PGPUB;	07:46
			EPO; JPO;	
	į		DERWENT	
-	52713	substrate with groove	USPAT;	2004/06/21
			US-PGPUB;	07:48
			EPO; JPO;	
			DERWENT	
-	483823	etch\$4	USPAT;	2004/06/21
			US-PGPUB;	07:48
			EPO; JPO;	
			DERWENT	
-	404	359/223-226,290-291.ccls. and MEMS	USPAT;	2004/06/21
			US-PGPUB;	07:48
			EPO; JPO;	
			DERWENT	
_	1	(359/223-226,290-291.ccls. and MEMS) and	USPAT;	2004/06/21
-	•	(bimorph same (silicon and aluminum))	US-PGPUB;	08:06
	i	ישווייין אווייין	1	
			EPO; JPO;	
	72040	wide de wide film	DERWENT	2004/06/24
-	73242	nitride with film	USPAT;	2004/06/21
			US-P PUB;	08:06
			EPO; JPO;	
	1		DERWENT	

•	36	(359/223-226,290-291.c Is. and MEMS) and	USPAT;	2004/06/21
		(nitride with film)	US-PGPUB;	08:08
			EPO; JPO;	
			DERWENT	
-	2	((359/223-226,290-291. Is. and MEMS) and	USPAT;	2004/06/21
		(nitride with film)) and (substrat with	US-PGPUB;	08:08
		groove)	EPO; JPO;	
			DERWENT	
-	15	(359/223-226,290-291.ccls. and MEMS) and	USPAT;	2004/06/21
		(substrate with groove)	US-PGPUB;	08:57
			EPO; JPO;	
			DERWENT	
-	97575	etch\$4 with silicon	USPAT;	2004/06/21
1			US-PGPUB;	08:57
			EPO; JPO;	
			DERWENT	
-	110827	potassium near2 hydroxide	USPAT;	2004/06/21
			US-PGPUB;	08:58
			EPO; JPO;	
			DERWENT	
-	60660	hydrazine	USPAT;	2004/06/21
			US-PGPUB;	08:58
			EPO; JPO;	
			DERWENT	
<b>-</b>	2461	((potassium near2 hydroxide) or hydrazine)	USPAT;	2004/06/21
		same (etch\$4 with silicon)	US-PGPUB;	08:58
			EPO; JPO;	
			DERWENT	
-	32	(((potassium near2 hydroxide) or hydrazine)	USPAT;	2004/06/21
		same (etch\$4 with silicon)) and	US-PGPUB;	08:58
		359/223-226,290-291.ccls.	EPO; JPO;	
			DERWENT	